

## **AMENDMENTS TO THE CLAIMS**

The following listing of claims will replace all prior versions and listings of claims in the application.

### **LISTING OF CLAIMS**

1-4. (Cancelled)

5. (Currently Amended) A wiring board production method comprising:

~~placing a mask on a substrate of a flexible printed circuit to expose each of a plurality of substrate terminals on the substrate through a corresponding opening in the mask, each opening in the mask being larger than the corresponding substrate terminal; applying solder through the openings in the mask to each of the plurality of substrate terminals;~~

forming a pair of substrate terminals on a substrate;

forming a conductive region between the pair of substrate terminals;

applying solder continuously across one of the substrate terminals and the conductive region to entirely cover one of the substrate terminals and at least partially cover a portion of the conductive region;

mounting an IC package, which has terminals and solder balls connected to the terminals, preformed with terminals on the substrate so that the terminals-solder balls of the IC package are aligned with corresponding substrate terminals through the applied solder;

melting the applied solder and the solder balls in a reflow process after mounting the IC package; and

performing the reflow process so as to divide the applied solder between the one substrate terminal and the portion of the conductive region.

6-7. (Cancelled)

8. (Currently Amended) A wiring board production method according to claim ~~7~~5, wherein the conductive region is a wiring line extending from the substrate terminals.

9. (Currently Amended) A wiring board which is produced by the wiring board production method according to claim ~~5~~8.

10. (Original) An electrooptical apparatus production method including a step of implementing the wiring board production method according to claim 5.

11. (Original) An electrooptical apparatus which is produced by the electrooptical apparatus production method according to claim 10.

12. (Original) An electronic device production method including a step of implementing the electrooptical apparatus production method according to claim 10.

13. (Original) An electronic device which is produced by the electronic device production method according to claim 12.

14. (New) A wiring board which is produced by the wiring board production method according to claim 5.